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1-of-8 Decoder/Demultiplexer



ADE-205-368 (Z) 1st. Edition Sep. 2000

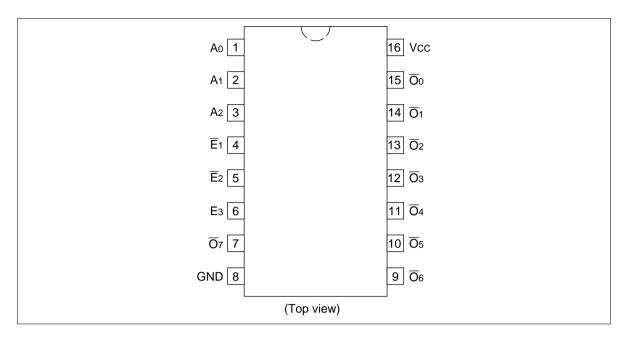
Description

The HD74AC138/HD74ACT138 is a high-speed 1-of-8 decoder/demultiplexer. This device is ideally suited for high-speed bipolar memory chip select address decoding. The multiple input enables allow parallel expansion to a 1-of-24 decoder using just three HD74AC138/HD74ACT138 devices or a 1-of-32 decoder using four HD74AC138/HD74ACT138 devices and one inverter.

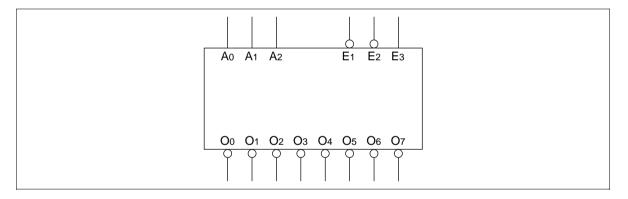
Features

- Demultiplexing Capability
- Multiple Input Enable for Easy Expansion
- Active LOW Mutually Exclusive Outputs
- Outputs Source/Sink 24 mA
- HD74ACT138 has TTL-Compatible Inputs

Pin Arrangement



Logic Symbol



Pin Names

A_0 to A_2	Address Inputs
$\overline{\mathrm{E}}_{1}$ to $\overline{\mathrm{E}}_{2}$	Enable Inputs
E ₃	Enable Input
\overline{O}_0 to \overline{O}_7	Outputs



Functional Description

The HD74AC138/HD74ACT138 high-speed 1-of-8 decoder/demultiplexer accepts three binary weighted inputs (A₀, A₁, A₂) and, when enabled, provides eight mutually exclusive active-LOW outputs (\overline{O}_0 to \overline{O}_7). The HD74AC138/HD74ACT138 features three Enable inputs, two active-Low (\overline{E}_1 , \overline{E}_2) and one active-High (E₃). All outputs will be High unless \overline{E}_1 and \overline{E}_2 are Low and E₃ is High. This multiple enabled function allows easy parallel expansion of the device to a 1-of-32 (5 lines to 32 lines) decoder with just four HD74AC138/HD74ACT138 devices and one inverter (See Figure a). The HD74AC138/HD74ACT138 can be used as an 8-output demultiplexer by using one of the active Low Enable inputs as the data input and the other Enable inputs as strobes. The Enables inputs which are not used must be permanently tied to their appropriate active-High or active-Low state.

Inputs					Outp	Outputs							
$\overline{\mathbf{E}}_{1}$	\overline{E}_{2}	E3	A ₀	A ₁	A ₂	$\overline{\mathbf{O}}_{0}$	$\overline{\mathbf{O}}_{1}$	$\overline{\mathbf{O}}_{2}$	$\overline{\mathbf{O}}_{3}$	$\overline{\mathbf{O}}_{4}$	$\overline{\mathbf{O}}_{5}$	$\overline{\mathbf{O}}_{6}$	0 7
Н	Х	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	Н	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	Х	L	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
L	L	Н	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	L	Н	Н	L	L	Н	L	Н	Н	Н	Н	Н	Н
L	L	Н	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
L	L	Н	Н	Н	L	Н	Н	Н	L	Н	Н	Н	Н
L	L	Н	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н
L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
L	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

Truth Table

H : High Voltage Level

L : Low Voltage Level

X : Immaterial

Logic Diagram

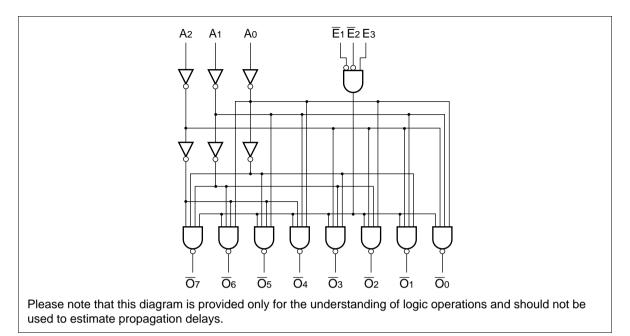
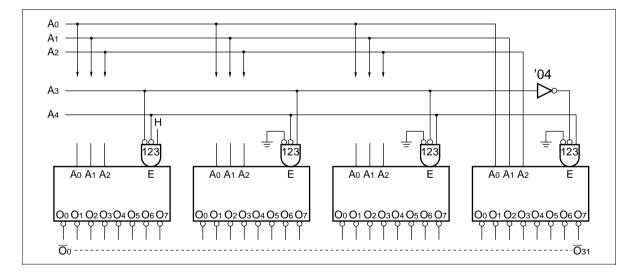


Figure a: Expansion of 1-of-32 Decoding





DC Characteristics (unless otherwise specified)

Item	Symbol	Max	Unit	Condition
Maximum quiescent supply current	I _{cc}	80	μΑ	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5$ V, Ta = Worst case
Maximum quiescent supply current	I _{cc}	8.0	μΑ	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5$ V, Ta = 25°C
Maximum I _{cc} /input (HD74ACT138)	I _{CCT}	1.5	mA	$V_{IN} = V_{CC} - 2.1 \text{ V}, V_{CC} = 5.5 \text{ V}$ Ta = Worst case

AC Characteristics: HD74AC138

				Ta = +25°C C _∟ = 50 pF		Ta = –4 C _∟ = 50		
ltem	Symbol	V _{cc} (V)* ¹	Min	Тур	Max	Min	Max	Unit
Propagation delay	t _{PLH}	3.3	1.0	8.5	13.0	1.0	15.0	ns
A_n to \overline{O}_n		5.0	1.0	6.5	9.5	1.0	10.5	
Propagation delay	t _{PHL}	3.3	1.0	8.0	12.5	1.0	14.0	ns
A_n to \overline{O}_n		5.0	1.0	6.0	9.0	1.0	10.5	
Propagation delay	t _{PLH}	3.3	1.0	11.0	15.0	1.0	16.0	ns
\overline{E}_1 or \overline{E}_2 to \overline{O}_n		5.0	1.0	8.0	11.0	1.0	12.0	
Propagation delay	t _{PHL}	3.3	1.0	9.5	13.5	1.0	15.0	ns
\overline{E}_1 or \overline{E}_2 to \overline{O}_n		5.0	1.0	7.0	9.5	1.0	10.5	_
Propagation delay	t _{PLH}	3.3	1.0	11.0	15.5	1.0	16.5	ns
E_3 to \overline{O}_n		5.0	1.0	8.0	11.0	1.0	12.5	
Propagation delay	t _{PHL}	3.3	1.0	8.5	13.0	1.0	14.0	ns
E_3 to \overline{O}_n		5.0	1.0	6.0	8.0	1.0	9.5	

Note: 1. Voltage Range 3.3 is $3.3 \text{ V} \pm 0.3 \text{ V}$ Voltage Range 5.0 is $5.0 \text{ V} \pm 0.5 \text{ V}$

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AC Characteristics: HD74ACT138

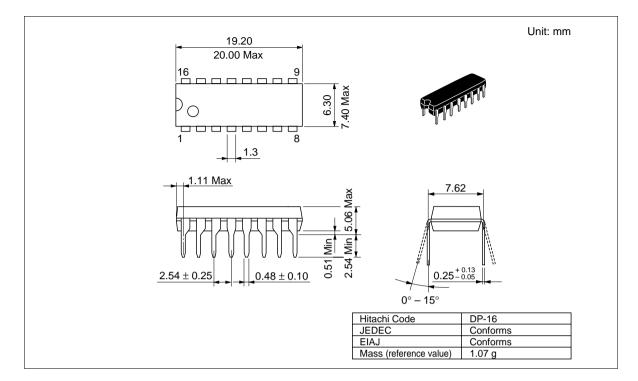
			Ta = +25°C C _∟ = 50 pF		Ta = –4 C _∟ = 50			
Item	Symbol	V _{cc} (V)* ¹	Min	Тур	Max	Min	Max	Unit
Propagation delay An to \overline{O}_n	t _{PLH}	5.0	1.0	7.0	10.5	1.0	11.5	ns
Propagation delay An to \overline{O}_n	t _{PHL}	5.0	1.0	6.5	10.5	1.0	11.5	ns
Propagation delay \overline{E}_1 or \overline{E}_2 to \overline{O}_n	t _{PLH}	5.0	1.0	8.0	11.5	1.0	12.5	ns
Propagation delay \overline{E}_1 or \overline{E}_2 to \overline{O}_n	t _{PHL}	5.0	1.0	7.5	11.5	1.0	12.5	ns
Propagation delay E_3 to \overline{O}_n	t _{PLH}	5.0	1.0	8.0	12.0	1.0	13.0	ns
Propagation delay E_3 to \overline{O}_n	t _{PHL}	5.0	1.0	6.5	10.5	1.0	11.5	ns

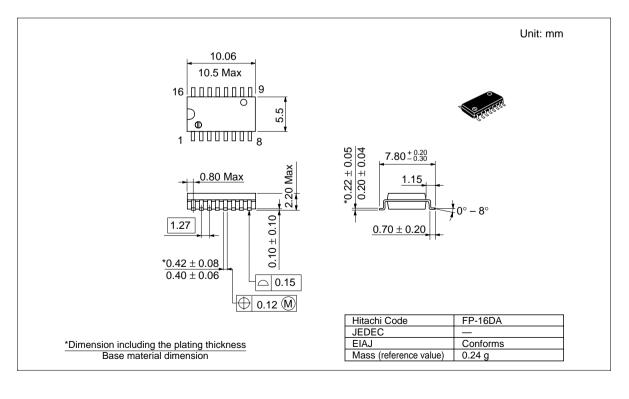
Note: 1. Voltage Range 5.0 is $5.0 \text{ V} \pm 0.5 \text{ V}$

Capacitance

Item	Symbol	Тур	Unit	Condition
Input capacitance	CIN	4.5	pF	$V_{cc} = 5.5 V$
Power dissipation capacitance	C _{PD}	60.0	pF	$V_{cc} = 5.0 V$

Package Dimensions







 $*0.22^{+0.08}_{-0.07}$

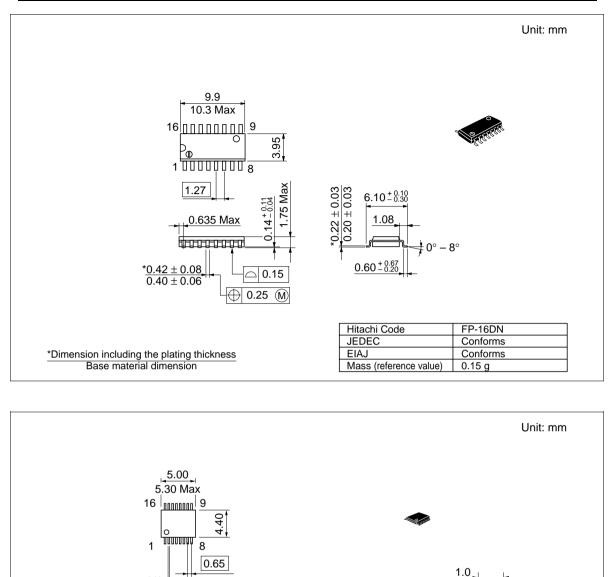
1.10 Max

 0.20 ± 0.06

🕀 0.13 🕅

○ 0.10

<mark>-||⊲</mark>0.65 Max (mmmm)



 $\frac{*0.17 \pm 0.05}{0.15 \pm 0.04}$ Hitachi Code TTP-16DA JEDEC EIAJ *Dimension including the plating thickness 0.05 g Base material dimension Mass (reference value)

 $0.07^{+0.03}_{-0.04}$

 6.40 ± 0.20

₽0° – 8°

 0.50 ± 0.10

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